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PAGES: 4 including cover

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THANK YOU.

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attachment to interview held May 16, 2011
& entered in scanned file May 17, 2011

Attorney Docket No.: 0553-0408

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Shinji MAEKAWA et al.)
)
Serial No.: 10/827,457)
)
Filed: April 19, 2004)
)
For: Method For Forming Pattern And)
Drop Discharge Apparatus)
)
Examiner: Marianne L. Padgett)
)
Art Unit: 1715)
)
Confirmation No.: 2984)

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

PROPOSED AMENDMENT L

Applicants have the following response to the Office Action of February 16, 2011.

Please amend the above-identified application as follows:

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A pattern forming method comprising steps of:

forming a thin film on a surface;

positioning the surface and ~~[[,]]~~ a first nozzle and a second nozzle, ~~the first and the second nozzles being integrated,~~ so that the first nozzle is ~~and the second nozzle are~~ in a region located above a selected portion of the thin film;

irradiating the selected portion of the ~~liquid-repellent~~ thin film with ~~[[a]]~~ plasma ~~[[of a]]~~ gas irradiated ~~originating~~ from the first nozzle to selectively provide affinity for ~~[[the]]~~ a liquid composition to the selected portion, after the step of positioning the ~~integrated~~ first nozzle ~~and the integrated second nozzle;~~ and

applying ~~[[a]]~~ the liquid composition to the selected portion by discharging a drop from ~~[[the]]~~ a second nozzle by drop discharging method, after having irradiated the selected portion with ~~[[the]]~~ plasma gas,

forming a pattern by repeating said steps of positioning, irradiating, and applying,

etching the thin film by plasma etching using plasma gas irradiated ~~sprayed~~ by an array of nozzles over an area including the selected portion of the thin film and the pattern, and using the pattern as mask;

wherein a larger quantity of plasma gas is irradiated sprayed over regions where the thin film is exposed than over the pattern ~~varies according to the pattern.~~

The undersigned wishes to discuss this claim and the 112 rejection with the Examiner.

Date:

Respectfully submitted,

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